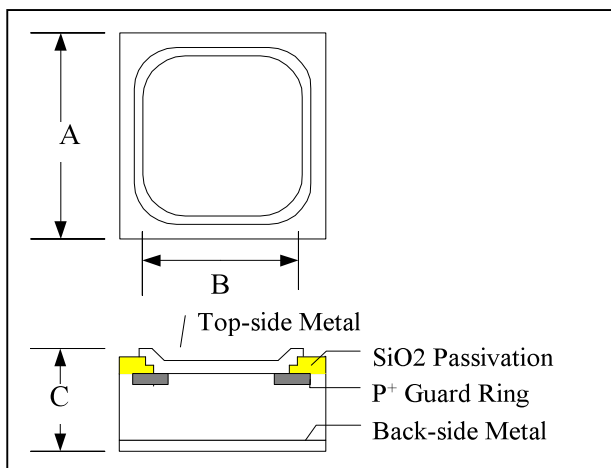


ELECTRICAL CHARACTERISTICS	SYM	Spec. Limit	UNIT
Reverse Breakdown Voltage: Ir=0.50mA	VBRM	43	Volt
Average Rectified Forward Current	IFAV	1.0	Amp
Maximum Instantaneous Forward Voltage			
@ 1 Amperes, Ta=25°C	VF MAX	0.490	Volt
Maximum Instantaneous Reverse Current			
VR= 40 Volt, Ta=25°C	IR MAX	0.050	mA
ESD Level (IEC61000-4-2 test method)	Level 2	±4kV (air) ±4kV (contact)	
<b>MAXIMUM RATINGS</b>			
Nonrepetitive Peak Surge Current Semi-Sine Wave, Duty = 8.3ms · 1cycle	IFSM	30	Amp
Operating Junction Temperature	Tj	125	°C
Storage Temperatures	TSTG	-50 to +150	°C

1. Specification is applied to die only. Actual performance may degrade when assembled. BW does not guarantee device performance after assembly.
2. Suggest to storage in Nitrogen cabinet, 45-60% RH, 22-26 °C for 6 months.
3. Data sheet information is subjected to change without notice.
4. Suggest Soldering profile (Pb92.5%,5%Sn,Ag2.5%): Soldering peak Temp. 340~350 °C 3~5min.
5. According to the IEC61000-4-2 standard, contact discharge is the preferred test method. Air discharge shall be used when contact discharge cannot be applied. In case of air discharge, the current level and rise time are less reproducibile and more related to environmental conditions (humidity, speed of the tip approach etc.).

**DICE OUTLINE DRAWING**



DIM	ITEM	μ m	Mil
A	Die Size	711	28.00
B	Top Metal Pad Size	591	23.30
C	Thickness	254	10.00

- (1) Cutting street width is around 40μm.
- (2) Both of top-side and back-side metals are Ti/Ni/Ag.
- (3) Top-side Ti/Ni thk: 0.42μm, Ag thk: 3.5μm
- (4) Thickness(C) tolerance: +/-10μm